

AT3216 Series

Multilayer Chip Antenna

Features

- ❖ Monolithic SMD with small, low-profile and light-weight type.
- ❖ Wide bandwidth
- ❖ RoHS compliant



Applications

- ❖ Bluetooth/Wireless LAN/Home RF
- ❖ ISM band 2.4GHz applications

Specifications

Part Number	Operating Frequency (MHz)	Peak Gain (XZ-total)	Average Gain (XZ-total)	VSWR	Impedance
AT3216 -A2R4PAA_	2400 ~ 2500	1.5 dBi typ.	-1.0 dBi typ.	3.0 max.	50Ω

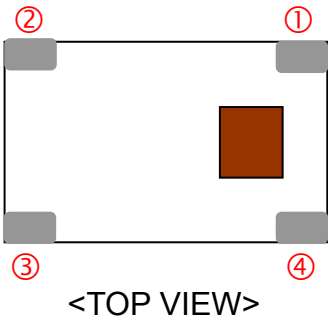
Q'ty/Reel (pcs) : 3,000pcs
 Operating Temperature Range : -40 ~ +125 °C
 Storage Temperature Range : -40 ~ +85 °C
 Storage Period : 12 months max.
 Power Capacity : 3W max.

Part Number

AT 3216 - A 2R4 PAA □ □
 ① ② ③ ④ ⑤ ⑥ ⑦

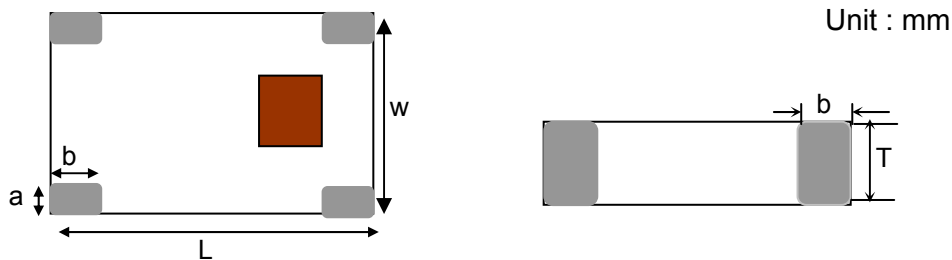
① Type	AT : Antenna	② Dimensions (L × W)	3.2× 1.6 mm
③ Material Code	A	④ Initial center frequency	2R4=2400MHz
⑤ Specification Code	PAA	⑥ Packaging	T: Tape & Reel B: Bulk
⑦ Soldering	/LF=lead-free		

Terminal Configuration



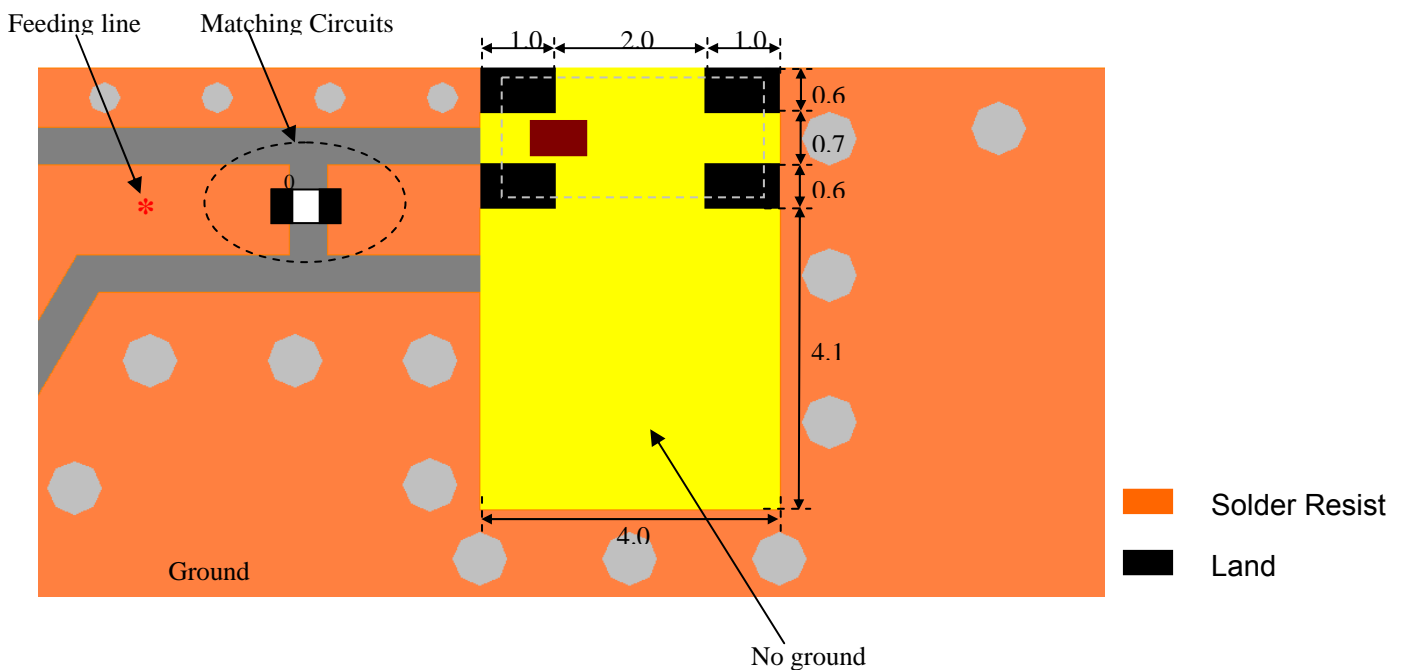
No.	Terminal Name	No.	Terminal Name
①	Feeding Point	②	GND
③	GND	④	GND

Dimensions and Recommended PC Board Pattern



Mark	L	W	T	a	b
Dimensions	3.2±0.2	1.6±0.2	1.2±0.2	0.3+0.1 /-0.2	0.5±0.2

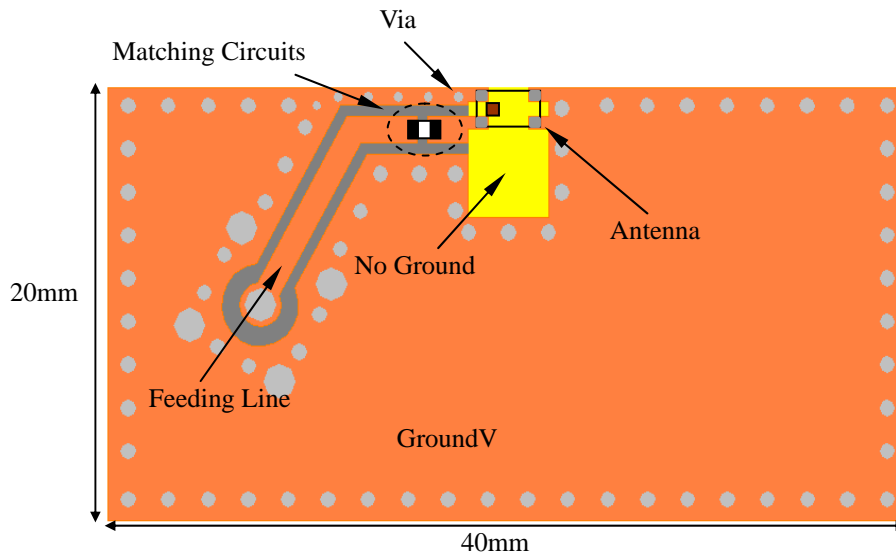
❖Without Matching Circuits - Unit in mm



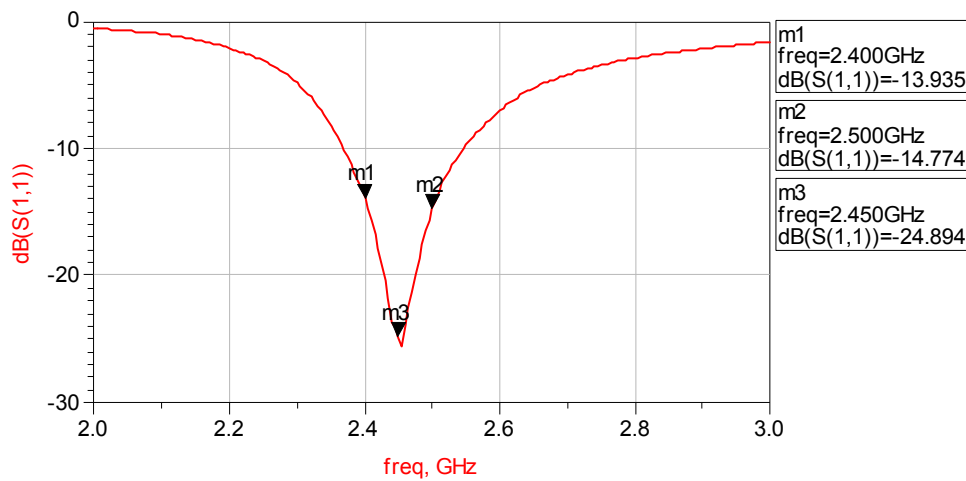
*Line width should be designed to match 50 characteristic impedance, depending on PCB material and thickness.

Typical Electrical Characteristics (T=25°C)

❖ Test Board

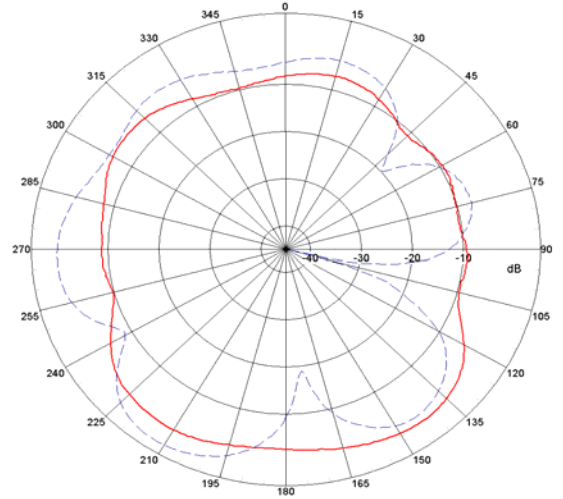
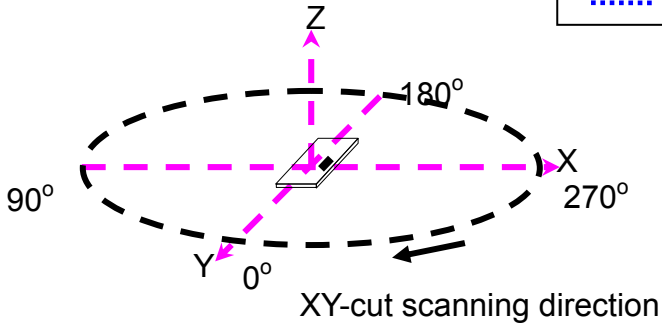


❖ Return Loss-without matching circuits

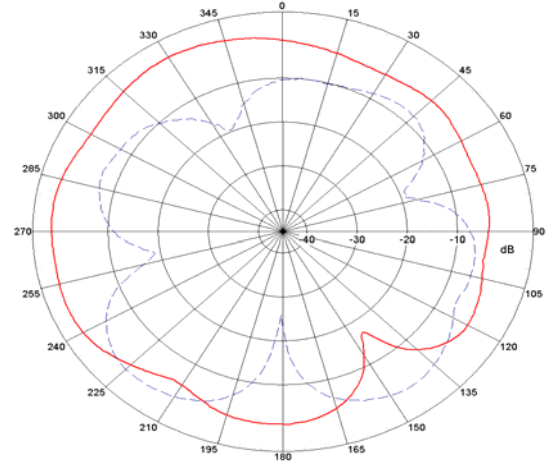
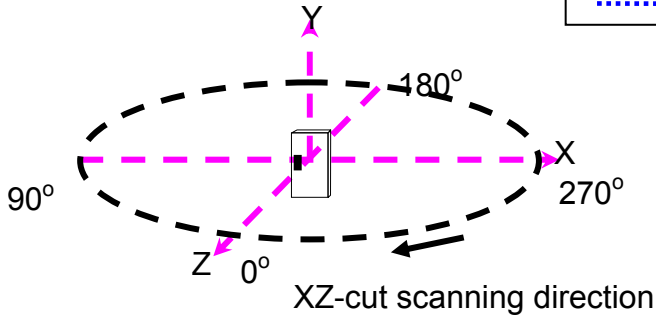


❖ Radiation Patterns

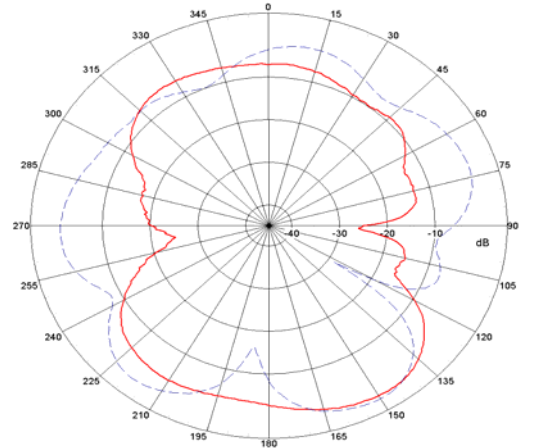
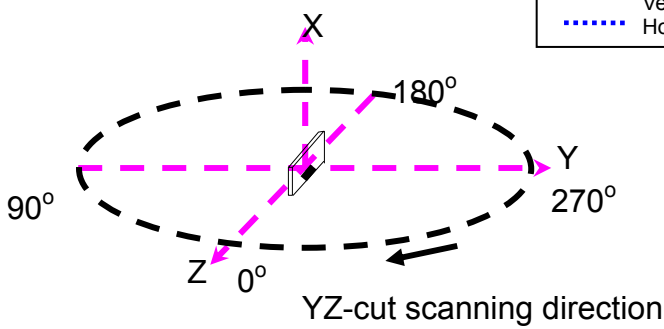
XY-V/XY-H



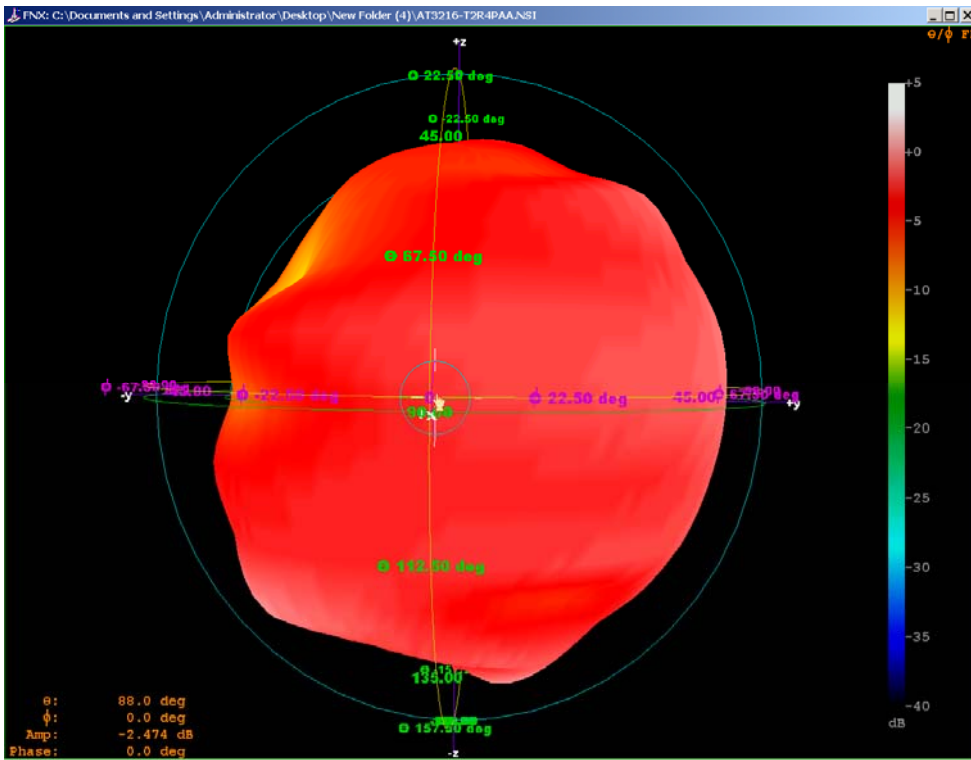
XZ-V/XZ-H



YZ-V/YZ-H

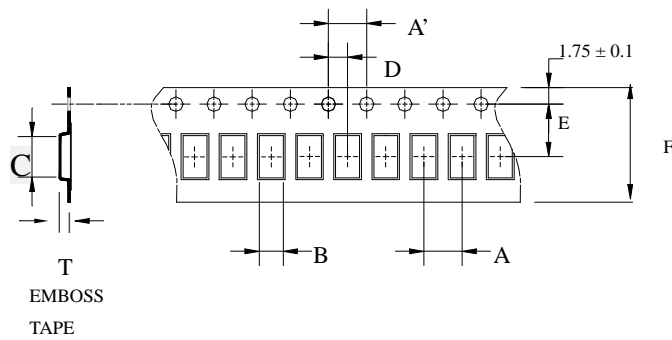


❖ Radiation Patterns - 3D Pattern



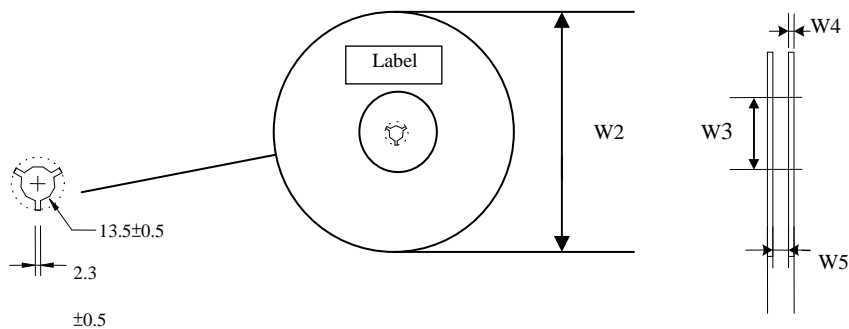
Taping Specifications

❖Tape & Reel Dimensions (Unit: mm) vs. Quantity (pcs)



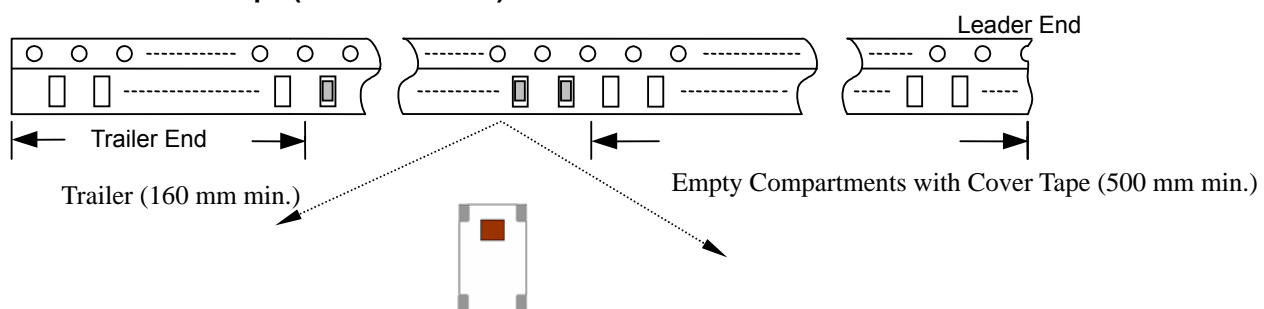
Type	A	A'	B	C	D	E	F	T	Quantity/per reel	Tape material
AT3216	4.0±	4.0±	1.88±	3.5±	2.0±	3.5±	8.00±	1.27±	3,000pcs	Plastic (Embossed)
	0.1	0.05	0.1	0.1	0.05	0.05	0.1	0.1		

❖Reel Dimensions (Unit: mm)

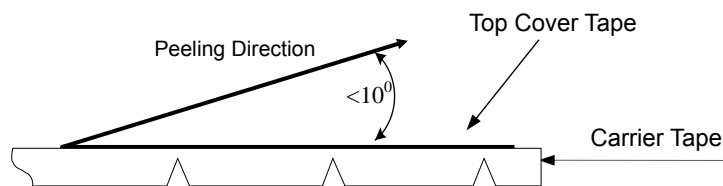


Type	W2	W3	W4	W5
AT3216	178±1	60±1	1.4±0.2	17±0.5

❖Leader and Trailer Tape (Plastic material)



❖ **Peel-off Force**



Peel-off force should be in the range of 0.1 – 0.6 N at a peel-off speed of 300 ± 10 mm/min .

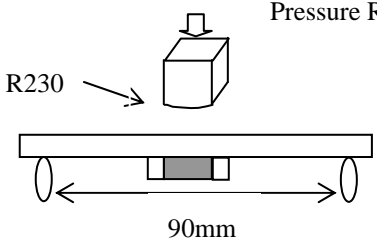
❖ **Storage Conditions**

- (1) Temperature: $5 \sim 35^{\circ}\text{C}$, relative humidity (RH): 45~75%.
- (2) Non-corrosive environment

Notes

❖ The contents of this data sheet are subject to change without notice. Please confirm the specifications and delivery conditions when placing your order.

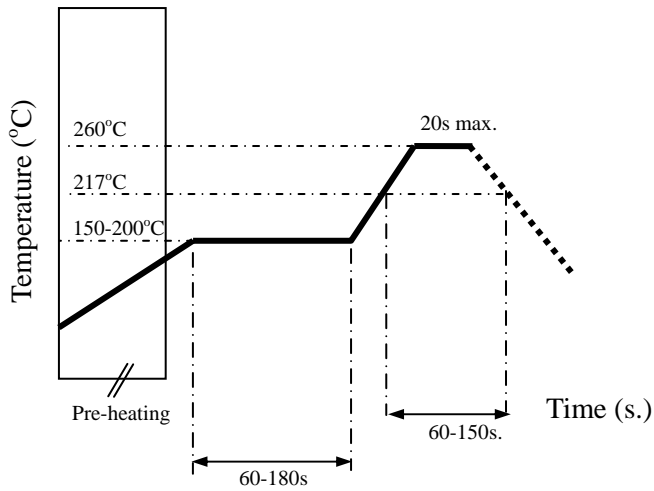
Mechanical & Environmental Characteristics

Item	Requirements	Procedure
Solderability	<ol style="list-style-type: none"> No apparent damage More than 95% of the terminal electrode shall be covered with new solder 	<ol style="list-style-type: none"> Preheat: $120 \pm 5^\circ\text{C}$ Solder: $245 \pm 5^\circ\text{C}$ for 5 ± 1 sec
Soldering strength (Termination Adhesion)	<ol style="list-style-type: none"> 1kg minimum 	<ol style="list-style-type: none"> Solder specimen onto test jig. Apply push force at 0.5mm/s until electrode pads are peeled off or ceramic are broken. Pushing force is applied to longitude direction
Deflection (Substrate Bending)	<ol style="list-style-type: none"> No apparent damage 	<ol style="list-style-type: none"> Solder specimen onto test jig (FR4, 0.8mm) using the recommend soldering profile. Apply a bending force of 2mm deflection 
Heat/Humidity Resistance	<ol style="list-style-type: none"> No apparent damage Fulfill the electrical specification after test 	<ol style="list-style-type: none"> Temperature: $85 \pm 2^\circ\text{C}$ Humidity: 90% ~ 95% RH Duration: 1000 ± 48hrs Recovery: 1-2hrs
Thermal shock (Temperature Cycle)	<ol style="list-style-type: none"> No apparent damage Fulfill the electrical specification after test 	<ol style="list-style-type: none"> One cycle/step 1 : $125 \pm 5^\circ\text{C}$ for 30 min step 2 : $-40 \pm 5^\circ\text{C}$ for 30 min No of cycles : 100 Recovery: 1-2 hrs
Low Temperature Resistance	<ol style="list-style-type: none"> No apparent damage Fulfill the electrical specification after test 	<ol style="list-style-type: none"> Temperature: $-40 \pm 5^\circ\text{C}$ Duration: 500 ± 24hrs Recovery: 1-2hrs

Soldering Conditions

❖ Typical Soldering Profile for Lead-free Process

Reflow Soldering :



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